Qualcomm

RF360
Europe GmbH

Data sheet

SAW filter
WLAN 2G

Part number:	B7544
Ordering code:	B39242B7544L210
Date:	May 10, 2022
Version:	2.1

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1 Application

- Low-loss SAW filter for WLAN / Bluetooth with LTE Band 7/ Band 38/ Band 40/ Band 41 coexistence
- WLAN 2G: 2442 MHz (pass band 77.8 MHz)
- Low insertion attenuation
- No matching required
- Very small package size

2 Features

- Package size $0.9_{\pm 0.05}$ mm × $0.7_{\pm 0.05}$ mm
- Package height 0.5 mm (max.)
- Approximate weight 1 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

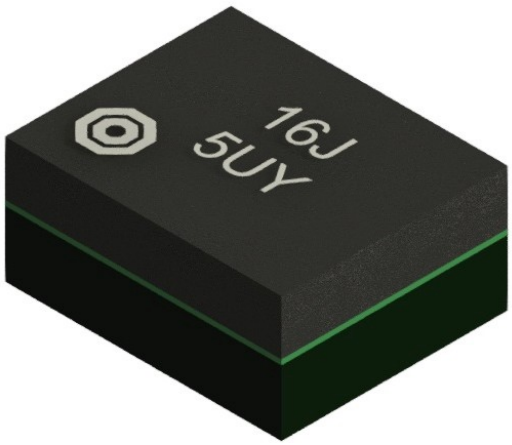

Figure 1: Picture of component with example of product marking.

3 Package

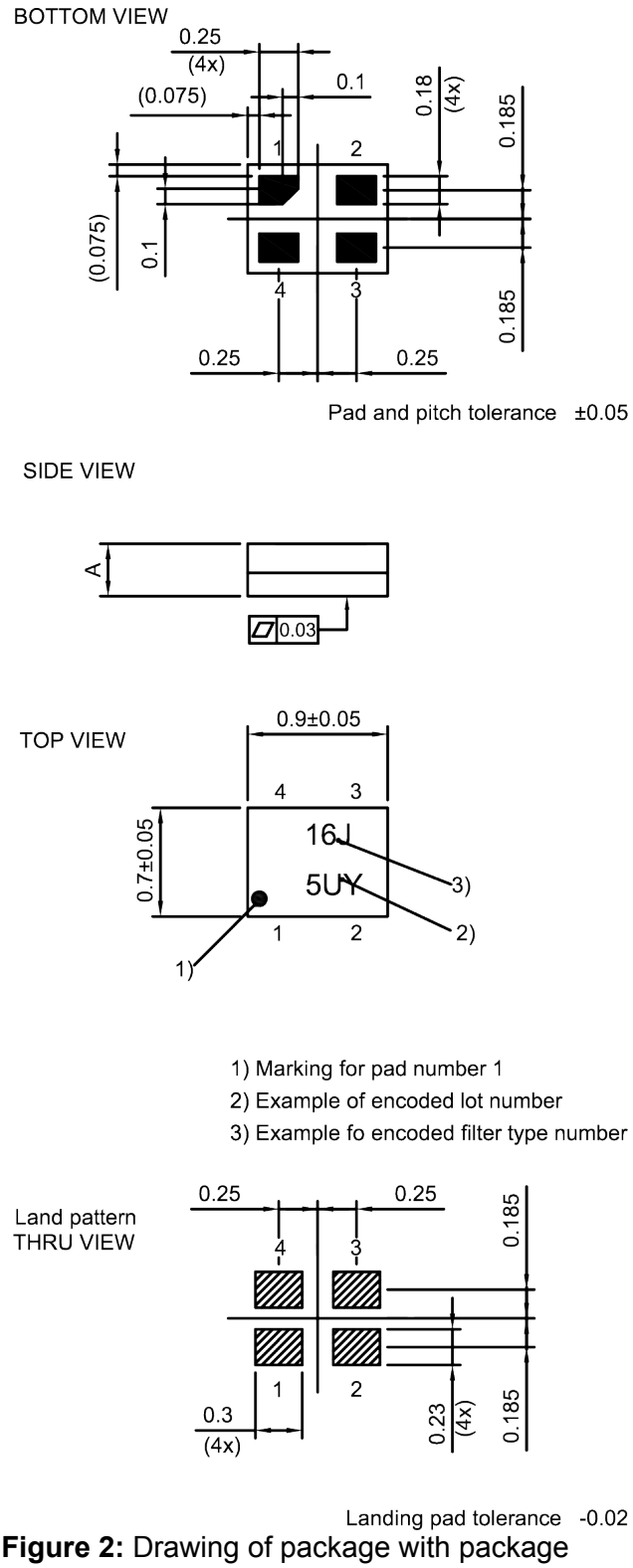

Figure 2: Drawing of package with package height A = 0.5 mm (max.). See Sec. Package information (p. 18).

4 Pin configuration

- 1 Input
- 3 Output
- 2, 4 Ground

5 Matching circuit

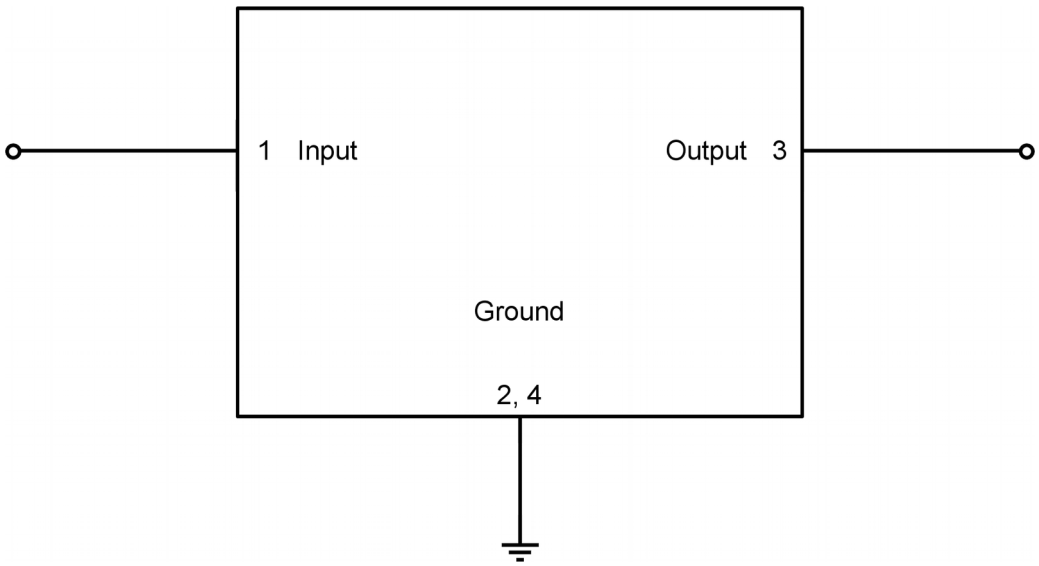

Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

Temperature range for specification T_{SPEC} = −20 °C ... +85 °C
Input terminating impedance Z_{IN} = 50 Ω
Output terminating impedance Z_{OUT} = 50 Ω

Characteristics				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	2442	—	MHz
Insertion attenuation – WLAN			α_{WLAN} [1]				
WiFi CH 1	2403.1 ... 2420.9	MHz		—	1.2	1.9	dB
WiFi CH 2	2408.1 ... 2425.9	MHz		—	1.1	1.6	dB
WiFi CH 3 - CH 11	2413.1 ... 2470.9	MHz		—	1.2	1.7	dB
WiFi CH 12	2458.1 ... 2475.9	MHz		—	1.3	1.9	dB
WiFi CH 13	2463.1 ... 2480.9	MHz		—	1.5	2.1 [2]	dB
Amplitude ripple (p-p)			Δα				
WiFi CH 1	2403.1 ... 2420.9	MHz		—	0.5	1.6	dB
WiFi CH 2	2408.1 ... 2425.9	MHz		—	0.4	1.1	dB
WiFi CH 3 - CH 11	2413.1 ... 2470.9	MHz		—	0.3	1.2	dB
WiFi CH 12	2458.1 ... 2475.9	MHz		—	0.5	2.1	dB
WiFi CH 13	2463.1 ... 2480.9	MHz		—	0.9	3.3 [2]	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	2403.1 ... 2480.9	MHz		—	1.5	2.0	
@ output port	2403.1 ... 2480.9	MHz		—	1.5	2.0	
Attenuation			α_{INT} [4]				
	2300 ... 2370	MHz		38	47	—	dB
	2370 ... 2380	MHz		15	41	—	dB
	2496 ... 2501	MHz		16 [5]	29	—	dB
	2496 ... 2501	MHz		8 [6]	29	—	dB
	2500 ... 2505	MHz		32 [5]	41	—	dB
	2500 ... 2505	MHz		20 [6]	41	—	dB
	2505 ... 2570	MHz		30	39	—	dB
Minimum attenuation			α_{min}				
	50 ... 960	MHz		30	33	—	dB
	960 ... 2000	MHz		30	32	—	dB
	2110 ... 2170	MHz		32	38	—	dB
	2570 ... 7000	MHz		30	36	—	dB

[1] Average over each WLAN channel with band width of 17.8 MHz.
[2] Valid for temperature T = −20 °C...+65 °C.
[3] Within any 17.8 MHz.
[4] Integrated attenuation α_{INT}: Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.
[5] Valid for temperature T = +25 °C...+85 °C.
[6] Valid for temperature T = 0 °C...+85 °C.

7 Maximum ratings

Operable temperature	T_{OP} = −40 °C ... +85 °C	
Storage temperature	T_{STG} [1)] = −40 °C ... +85 °C	
DC voltage	$\lvert V_{DC} \rvert$ [2)] = 0 V	
Input power @ input port: 2403.1 ... 2480.9 MHz	P_{IN} = 20 dBm [3)]	17.8 MHz WLAN signal for 5000 h @ 55 °C. Source and load impedance 50 Ω.

1) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
2) In case of applied DC voltage blocking capacitors are mandatory.
3) Expected lifetime according to accelerated power durability tests and wear out models.

8 Transmission coefficient

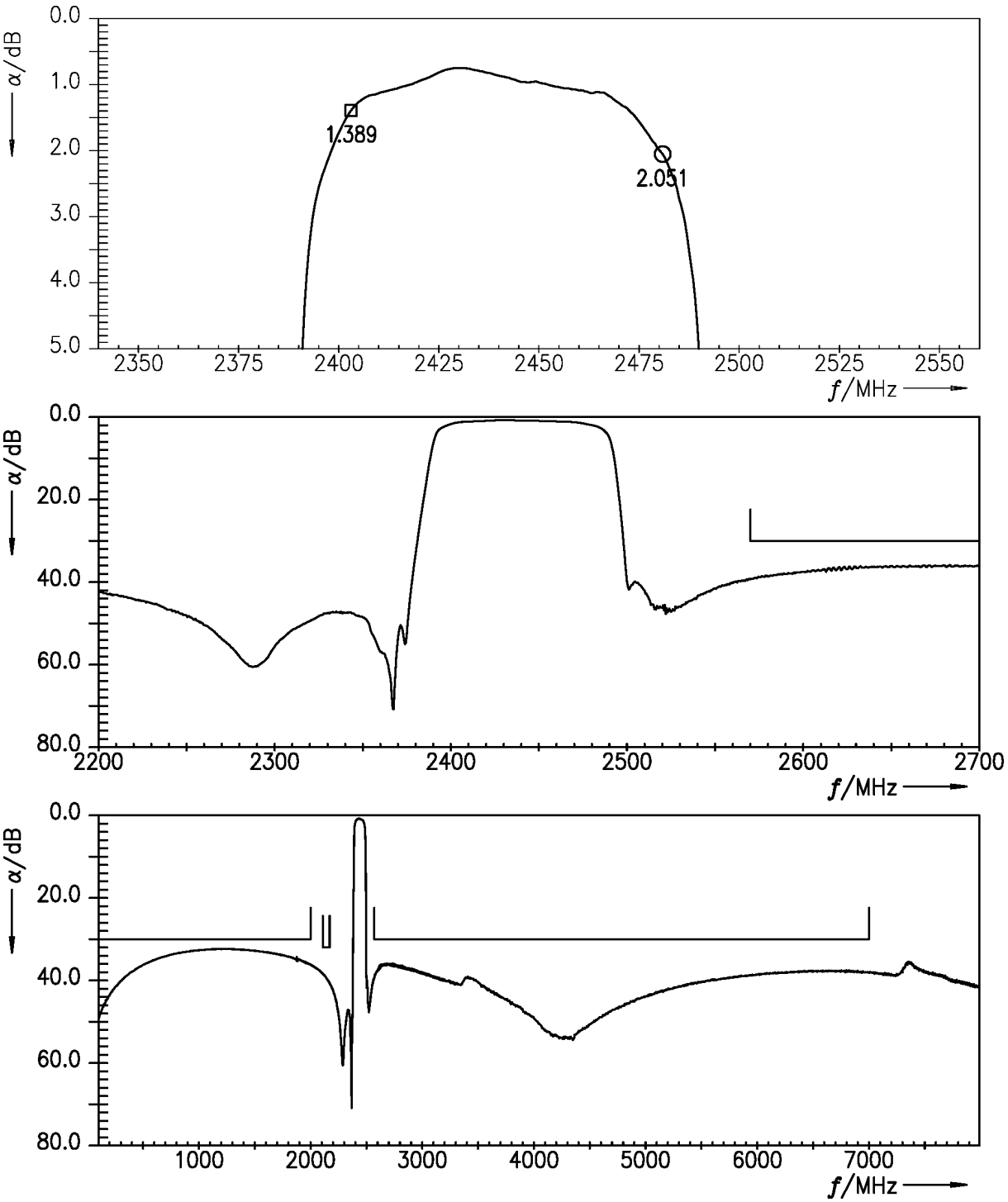

Figure 4: Attenuation.

9 Reflection coefficients

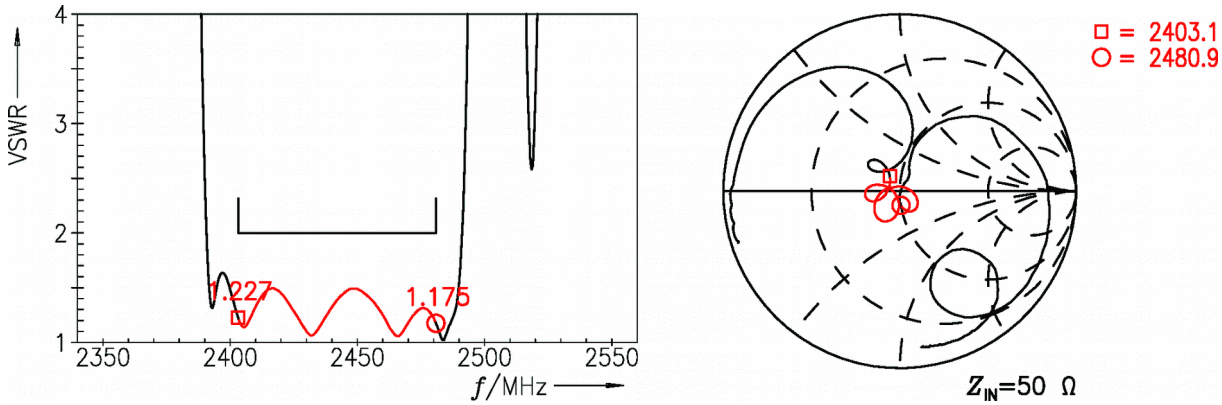

Figure 5: Reflection coefficient at input port.

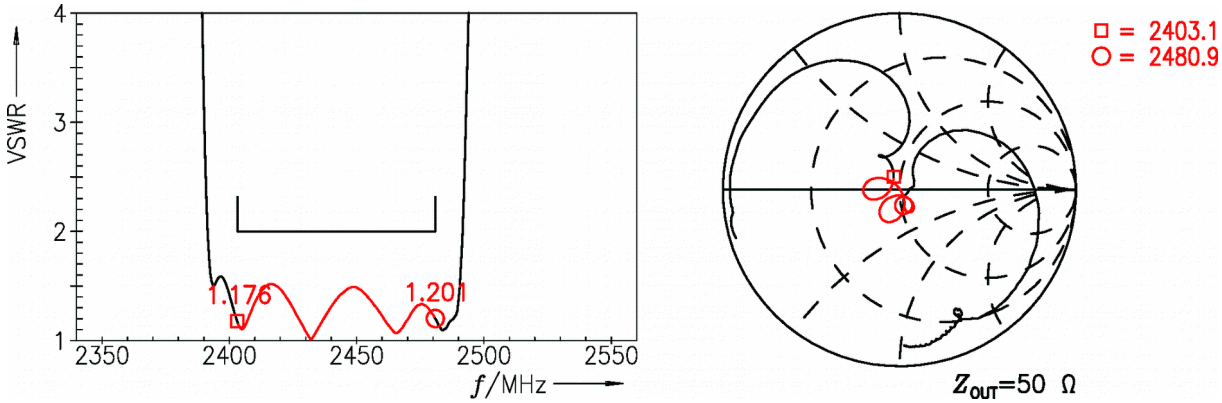

Figure 6: Reflection coefficient at output port.

10 Packing material

10.1 Tape

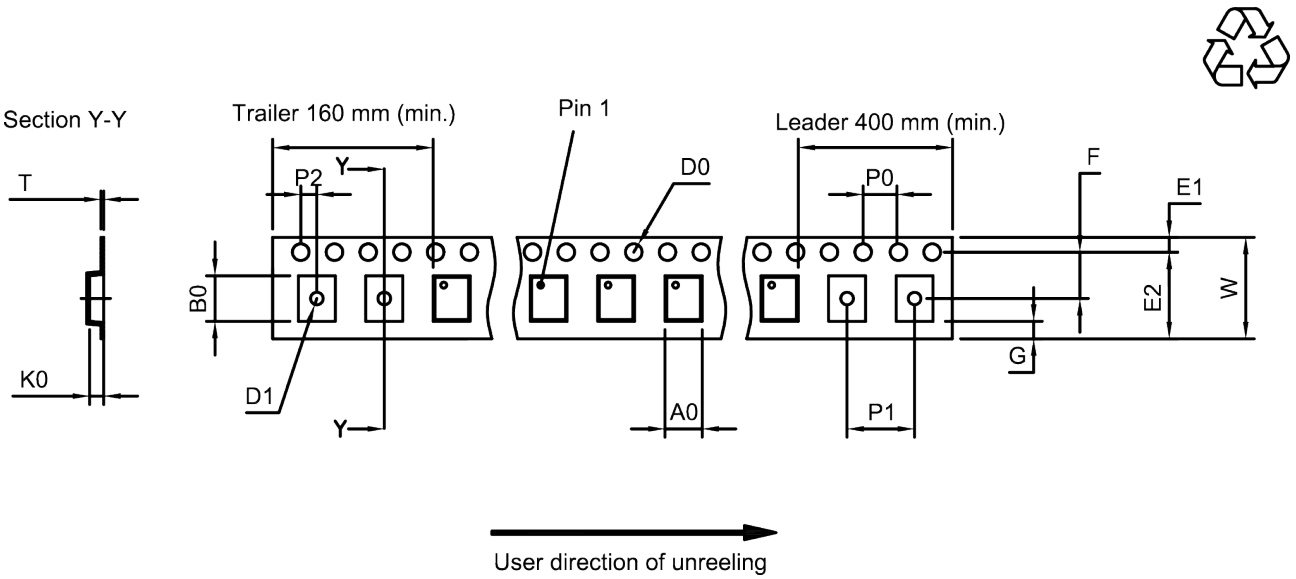

Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A_0	0.82±0.05 mm
B_0	1.02±0.05 mm
D_0	1.5+0.1/−0 mm
D_1	0.4±0.05 mm
E_1	1.75±0.1 mm

E_2	–
F	3.5±0.05 mm
G	0.75 mm (min.)
K_0	0.55±0.03 mm
P_0	4.0±0.1 mm

P_1	2.0±0.05 mm
P_2	2.0±0.05 mm
T	0.2±0.02 mm
W	8.0±0.1 mm

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

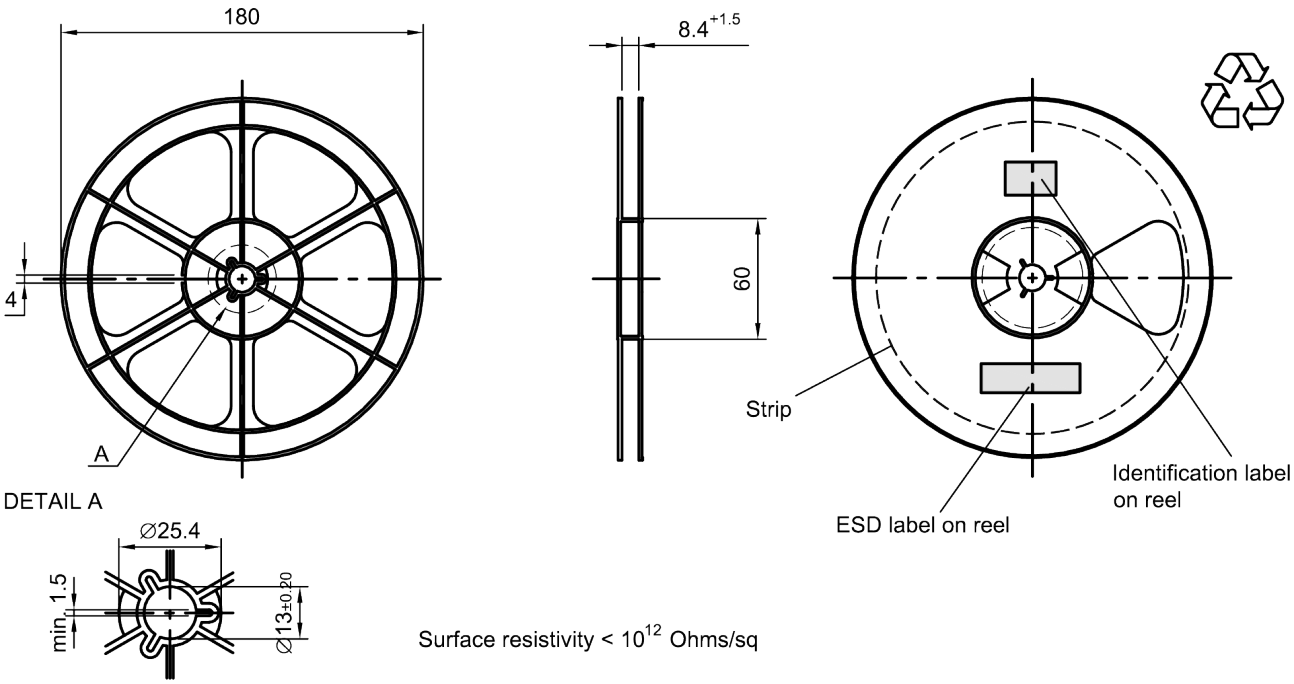

Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

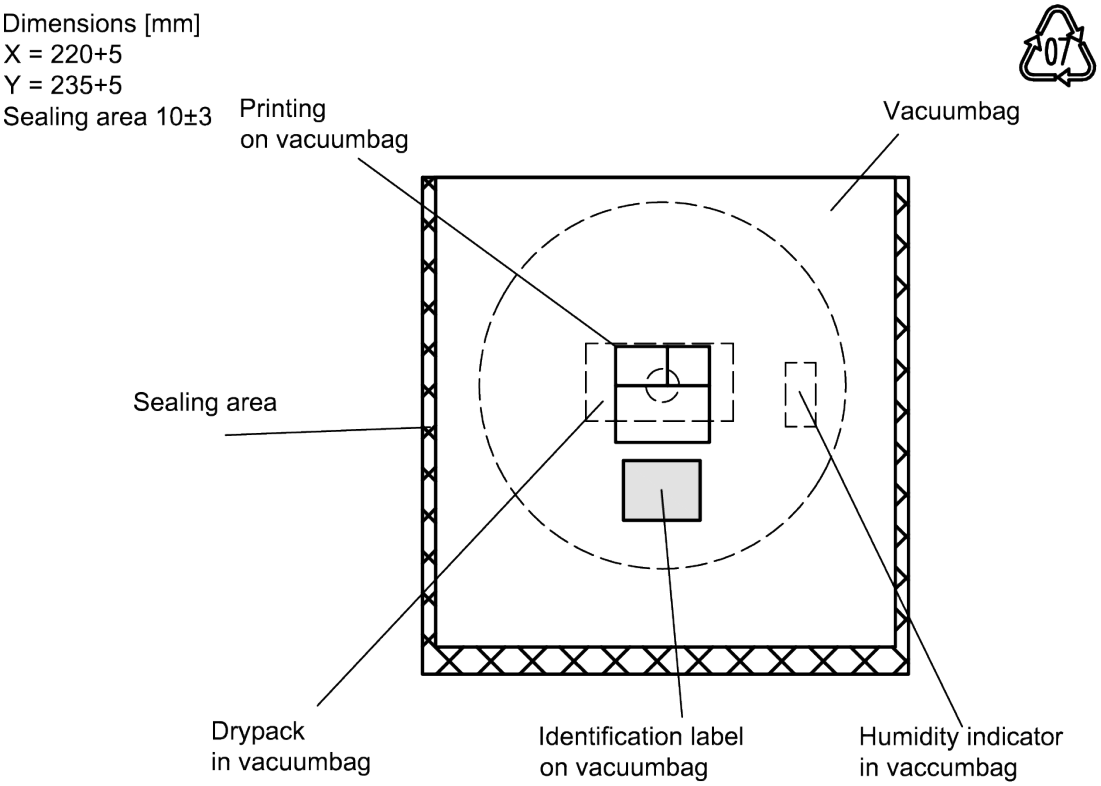

Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

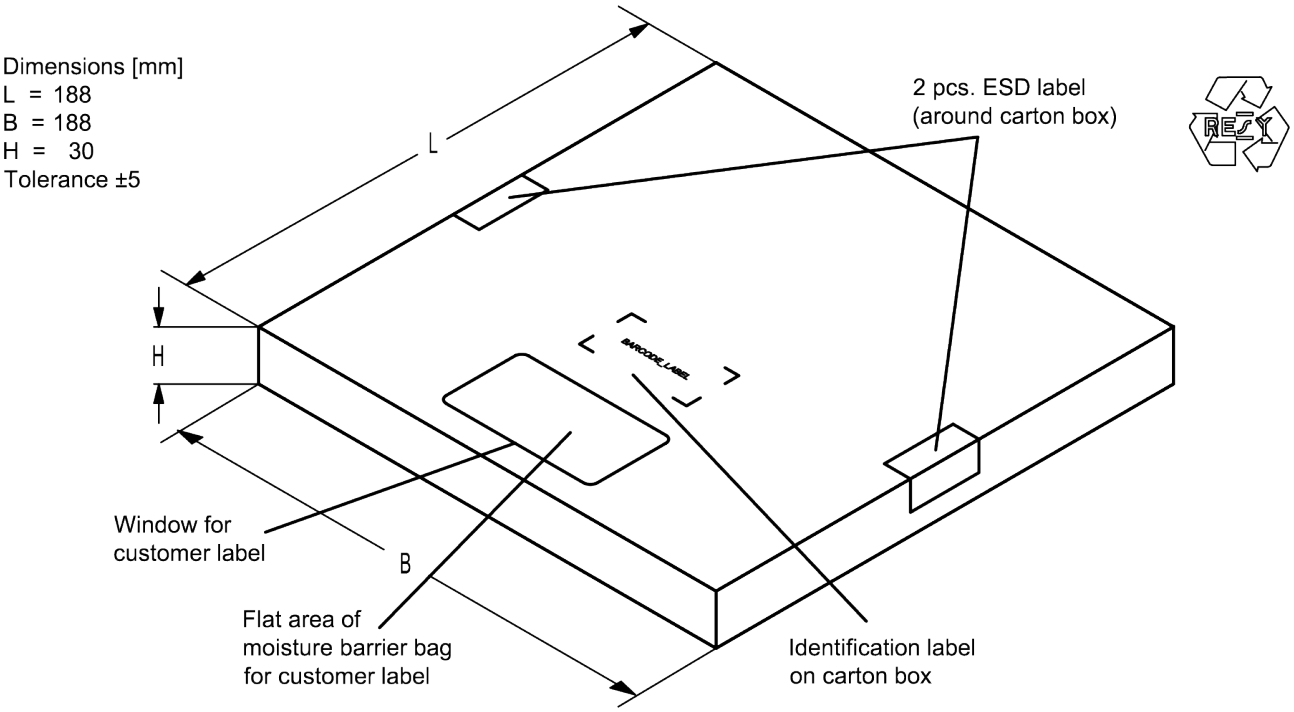

Figure 10: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm

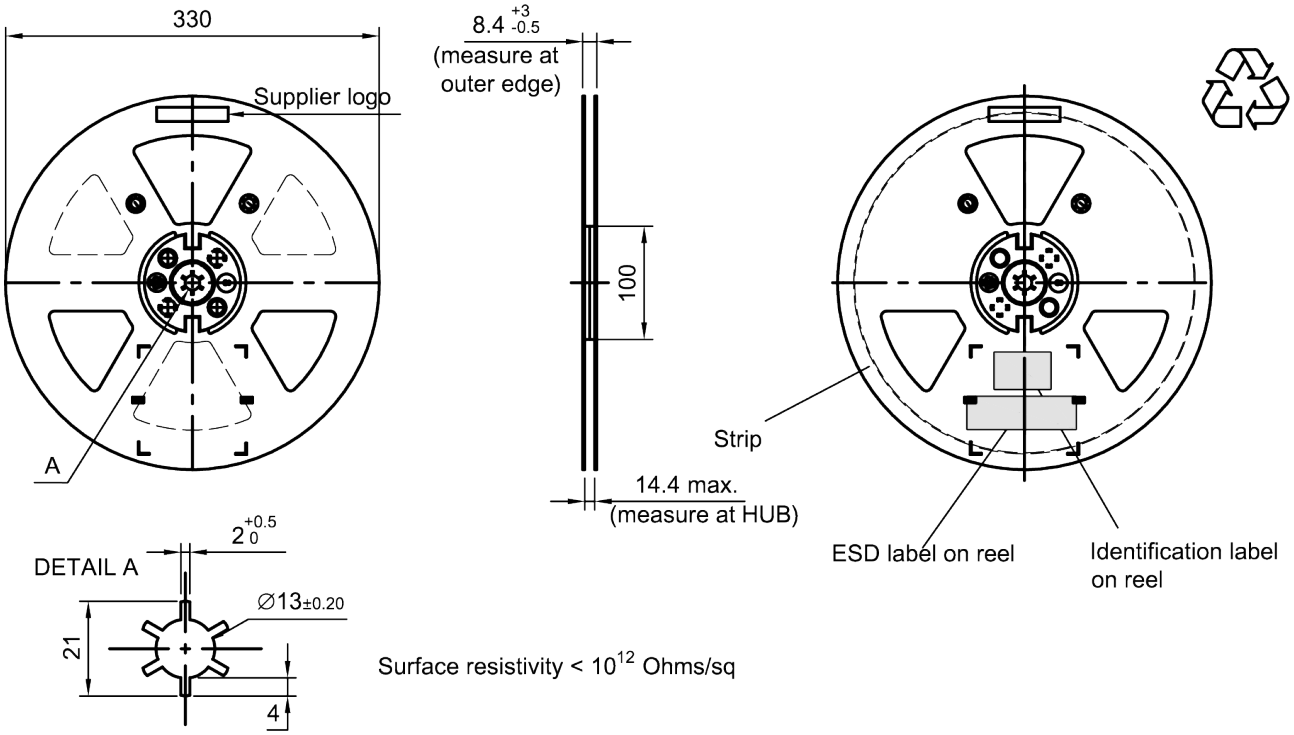

Figure 11: Drawing of reel (first-angle projection) with diameter of 330 mm.

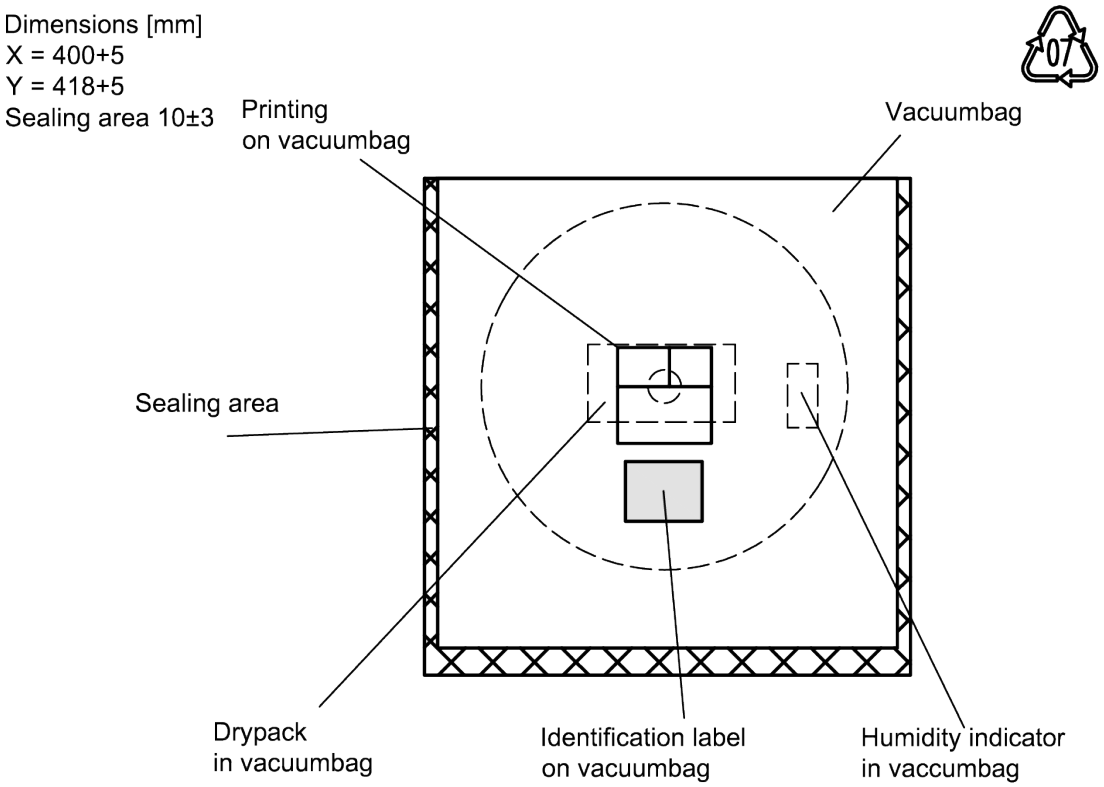

Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

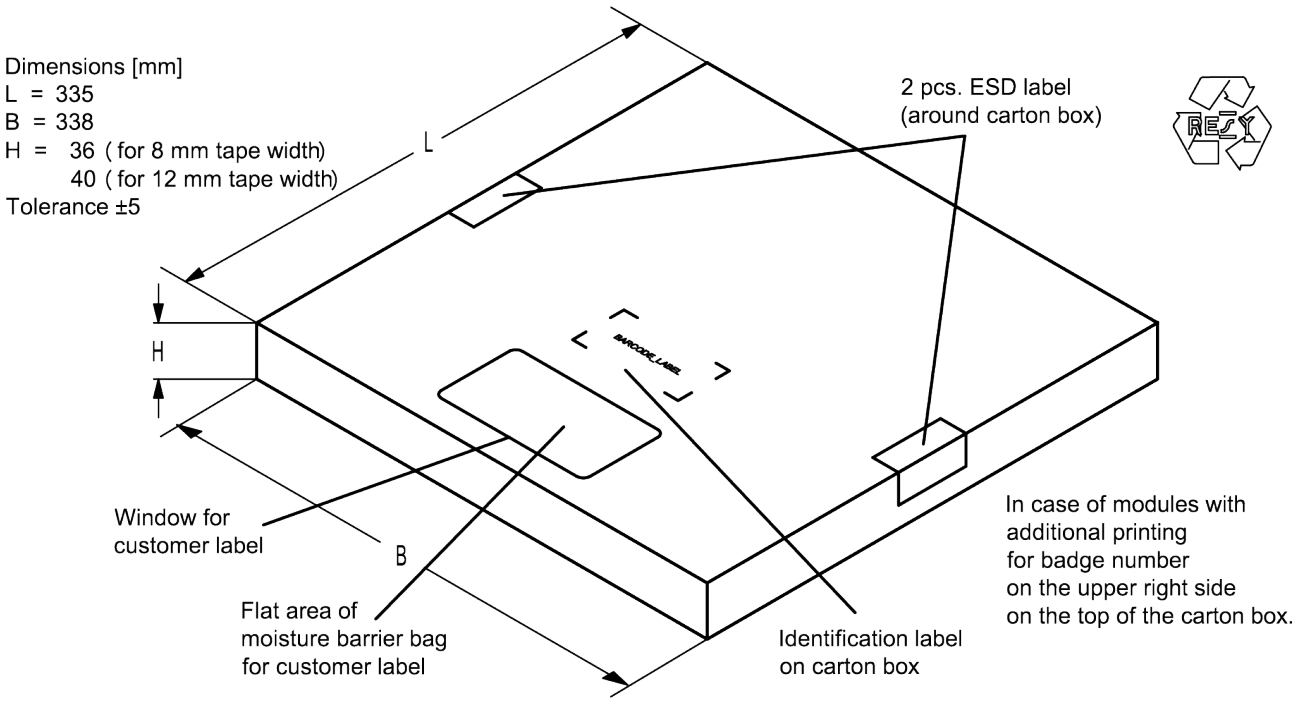

Figure 13: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

- Type number:

  The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
  is encoded by a special BASE32 code into a 3 digit marking.

  Example of decoding type number marking on device in decimal code.
  16J **=>** **1234**
  1 x 32^2 + **6** x 32^1 + **18 (=J)** x 32^0 **=** **1234**
  The BASE32 code for product type B7544 is 7BR.

- Lot number:

  The last 5 digits of the lot number, e.g., **12345**,
  are encoded based on a special BASE47 code into a 3 digit marking.

  Example of decoding lot number marking on device in decimal code.
  5UY **=>** **12345**
  5 x 47^2 + **27 (=U)** x 47^1 + **31 (=Y)** x 47^0 **=** **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

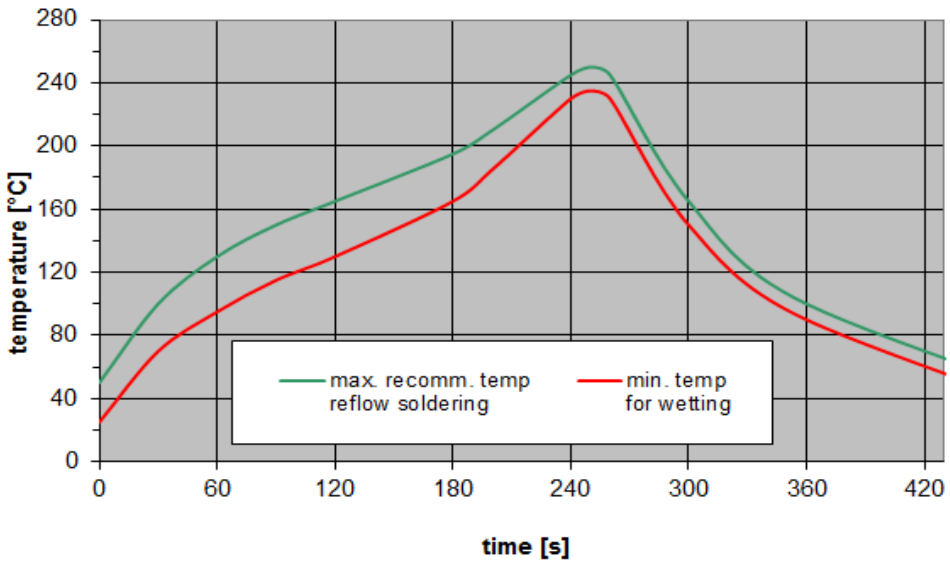

Figure 14: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Ordering codes / product IDs and packing units

Ordering code / product ID	RF360 label	Packing unit
B39242B7544L210	B39242-B7544-L210	5000 pcs

Table 4: Ordering codes / product IDs and packing units.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.qualcomm.com/.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

15 ESD protection of acoustic devices

Acoustic devices are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies must be applied.

In general, “ESD matching” must be ensured at that electrical port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the acoustic device must be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band acoustic devices the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and input port. The required component values must be determined from case to case.

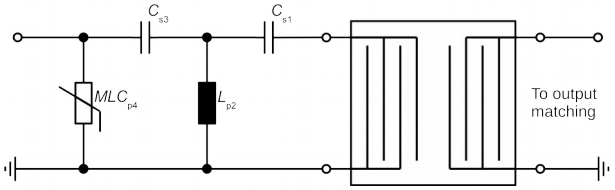

Figure 15: MLC varistor plus ESD matching.

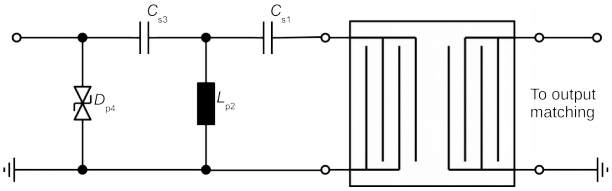

Figure 16: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

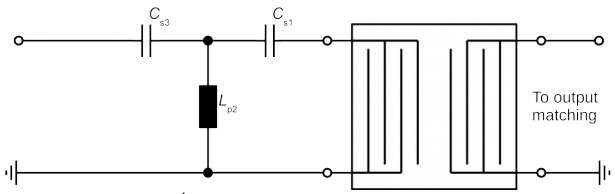

Figure 17: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: **“ESD protection for SAW filters”.** This report can be found under https://rffe.qualcomm.com.

16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (https://rffe.qualcomm.com). Should you have any more detailed questions, please contact our sales offices.
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